



Reminder for Call for Papers

Dear microelectronics and packaging colleagues,

This is to remind you of the abstract submission for the 23rd European Microelectronics and Packaging Conference and Exhibition. Deadline for submitting abstracts is on **January 19th**, 2021. Guarantee yourself a relaxing January and submit your abstract already during December 2020.

EMPC 2021 is jointly organised by **IMAPS Nordic**, **IEEE EPS** and **IMAPS Europe**. The event will present the best of microelectronics packaging and interconnection technologies, providing world class coverage of technological innovation in the microelectronics and packaging field with contributions from both industry and academia.

EMPC 2021 will be organised on the 13th to 16th of September 2021 in Gothenburg Sweden. Covid-19 situation is closely followed by the organising committee, and it is prepared to held the entire event virtually. Please see the covid-19 statement on the next page.

You are warmly welcome to submit your abstract(s) in the areas such as:

<p>Advanced Packaging</p> <ul style="list-style-type: none">• 3D integration, System-in Packages, FI- and FO-WLP, innovative interconnects, circuit solutions, Panel level packaging, Substrate and Interposer Technologies, emerging Heterogenous Integration Technologies <p>Advanced packaging for MEMS & sensors</p> <ul style="list-style-type: none">• Sensors, actuators and RF systems <p>Electronics Reliability & Quality</p> <ul style="list-style-type: none">• Methodology, Predictive maintenance, Novel reliability test methods., Modelling, Statistical reliability analysis and life models, Failure analysis and material characterization <p>Green Technologies</p> <ul style="list-style-type: none">• Recycling, supply chain, low power computing <p>Harsh environment applications</p> <ul style="list-style-type: none">• Aerospace, automotive, rail, washable wearables, smart farming, drilling, HTHP (high temperature and high pressure) O&G wells, geothermal energy and process industry	<p>Materials & Processes</p> <ul style="list-style-type: none">• Manufacturing and assembly technologies, new materials, compatibility, enabling materials, nano-materials and processes <p>Medical electronics</p> <ul style="list-style-type: none">• Implantable devices, miniaturization, neural interfaces, validation, new trends, reliability of implanted electronics, sensors for (implantable) medical devices <p>Opto-electronics</p> <ul style="list-style-type: none">• Packaging, light sources, detectors, photonic integrated circuits based on III-V/Si technology platforms, emerging materials, applications <p>Power electronics</p> <ul style="list-style-type: none">• Packaging, Thermal management, Wide Bandgap applications, Energy-conversion technologies, <p>Printed electronics</p> <ul style="list-style-type: none">• Materials and processes, Flexible, Structural, Applications (automotive, energy, medical, wearable and others)
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How to submit

We encourage you to start preparing your abstract. The abstract should be 300-500 words and may include images. First, create your profile at www.empc2021.org and follow the instructions for submitting the abstract. The site will be open for submission in September 2020.

Abstract deadline: Tuesday, January 19th, 2021.
Notification of acceptance: Tuesday, April 13th, 2021
Full manuscript submission: Tuesday, June 15th, 2021

Call for papers EMPC2021
www.empc2021.org



We hope to see you in Gothenburg in September 2021!

EMPC2021 statement on Covid19

The EMPC2021 committee is continuously monitoring the Covid19 situation with regards to how EMPC2021 will be organised in September next year.

The situation is currently extremely challenging as most countries are experiencing a second wave of infections. Even with promising news of vaccines, combating the Covid19 virus will still demand social distancing for some time to come, which sadly is not fully compatible with organising a conference.

At this time, the EMPC2021 committee is cautiously optimistic and thus still planning on a face-to-face conference in Gothenburg. However, as a back-up we are also doing preparations in case the conference will have to be online only. In that case we have chosen a solution called Trippus and will be organised by MeetX, that manages the conference secretariat. In our view, this solution will still enable social networking, both for participants, speakers and exhibitors. A presentation of the solution can be found at www.trippus.com.

To avoid unnecessary administration related to refunding parts of the registration fee to the conference, the registration will first require a reservation fee that is set to about 30% of the cost of the face-to-face conference. If the conference goes online, the reservation fee will cover the full registration at the online event. The reservation fee is non-refundable. If the conference is face-to-face, participants and exhibitors will have to pay the remaining registration fee before the conference.

The EMPC2021 committee targets making the decision whether to go face-to-face or online in April 2021 at the latest.

We hope you appreciate the committee's transparency regarding these decisions.

Stay safe and see you at EMPC2021!

EMPC 2021 Committee